



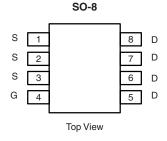
## P-Channel 30-V (D-S) MOSFET

| PRODUCT SUMMARY     |                                     |                    |  |  |
|---------------------|-------------------------------------|--------------------|--|--|
| V <sub>DS</sub> (V) | $R_{DS(on)}(\Omega)$                | I <sub>D</sub> (A) |  |  |
| - 30                | 0.0105 at V <sub>GS</sub> = - 10 V  | - 12.6             |  |  |
|                     | 0.0125 at V <sub>GS</sub> = - 4.5 V | - 11.5             |  |  |
|                     | 0.0195 at V <sub>GS</sub> = - 2.5 V | - 9.2              |  |  |

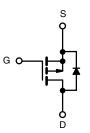
#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFETs
- Compliant to RoHS Directive 2002/95/EC





Ordering Information: Si4427BDY-T1-E3 (Lead (Pb)-free) Si4427BDY-T1-GE3 (Lead (Pb)-free and Halogen-free)



P-Channel MOSFET

| <b>ABSOLUTE MAXIMUM RATINGS</b> T <sub>A</sub> = 25 °C, unless otherwise noted |                        |                                   |             |              |      |  |
|--|------------------------|-----------------------------------|-------------|--------------|------|--|
| Parameter  |                        | Symbol                            | 10 s        | Steady State | Unit |  |
| Drain-Source Voltage   |                        | V <sub>DS</sub>                   | - 30        |              | V    |  |
| Gate-Source Voltage  |                        | V <sub>GS</sub>                   | ± 12        |              |      |  |
| Continuous Ducis Comment /T 450 9008   | T <sub>A</sub> = 25 °C | - I <sub>D</sub>                  | - 12.6      | - 9.7        |      |  |
| Continuous Drain Current (T <sub>J</sub> = 150 °C) <sup>a</sup>                | T <sub>A</sub> = 70 °C |                                   | - 10.1      | - 7.7        | Δ.   |  |
| Pulsed Drain Current   |                        | I <sub>DM</sub>                   | - 50        |              | Α    |  |
| Continuous Source Current (Diode Conduction) <sup>a</sup>                      |                        | I <sub>S</sub>                    | - 2.5       | - 1.3        |      |  |
|  | T <sub>A</sub> = 25 °C | - P <sub>D</sub>                  | 2.5         | 1.5          | W    |  |
| Maximum Power Dissipation <sup>a</sup>   | T <sub>A</sub> = 70 °C |                                   | 1.6         | 0.9          |      |  |
| Operating Junction and Storage Temperature Range                               |                        | T <sub>J</sub> , T <sub>stg</sub> | - 55 to 150 |              | °C   |  |

| THERMAL RESISTANCE RATINGS               |              |                     |         |         |      |
|--|--------------|---------------------|---------|---------|------|
| Parameter                                |              | Symbol              | Typical | Maximum | Unit |
| Marrian Instantantan Ameliand            | t ≤ 10 s     | - R <sub>thJA</sub> | 40      | 50      | °C/W |
| Maximum Junction-to-Ambient <sup>a</sup> | Steady State |                     | 70      | 85      |      |
| Maximum Junction-to-Foot (Drain)         | Steady State |                     | 15      | 18      |      |

a. Surface Mounted on 1" x 1" FR4 board.

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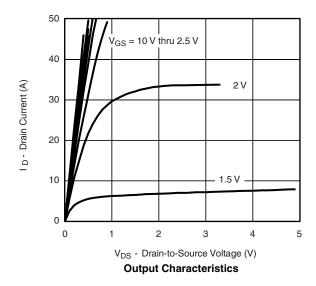
| Parameter                                     | Symbol              | Test Conditions  | Test Conditions Min. Typ. |               | Max.   | Unit |  |
|---|---------------------|--|---------------------------|---------------|--------|------|--|
| Static  |                     |  |                           | •             |        |      |  |
| Gate Threshold Voltage                        | V <sub>GS(th)</sub> | $V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$ - 0.60                         |                           | - 1.4         | V      |      |  |
| Gate-Body Leakage                             | I <sub>GSS</sub>    | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$                          |                           |               | ± 100  | nA   |  |
| Zero Gate Voltage Drain Current               | I <sub>DSS</sub>    | V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V                            |                           |               | - 1    |      |  |
|   |                     | V <sub>DS</sub> = - 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C    |                           |               | - 5    | μΑ   |  |
| On-State Drain Current <sup>a</sup>           | I <sub>D(on)</sub>  | $V_{DS} \le -5 \text{ V}, V_{GS} = -10 \text{ V}$                          | - 50                      |               |        | Α    |  |
| Drain-Source On-State Resistance <sup>a</sup> | R <sub>DS(on)</sub> | V <sub>GS</sub> = - 10 V, I <sub>D</sub> = - 12.6 A                        |                           | 0.0088        | 0.0105 |      |  |
|   |                     | V <sub>GS</sub> = - 4.5 V, I <sub>D</sub> = - 11.5 A                       |                           | 0.0105 0.0125 |        | Ω    |  |
|   |                     | V <sub>GS</sub> = - 2.5 V, I <sub>D</sub> = - 5.1 A                        |                           | 0.0150        | 0.0195 |      |  |
| Forward Transconductance <sup>a</sup>         | 9 <sub>fs</sub>     | V <sub>DS</sub> = - 15 V, I <sub>D</sub> = - 12.6 A                        |                           | 44            |        | S    |  |
| Diode Forward Voltage <sup>a</sup>            | $V_{SD}$            | I <sub>S</sub> = - 2.5 A, V <sub>GS</sub> = 0 V                            |                           | - 0.8         | - 1.2  | V    |  |
| Dynamic <sup>b</sup>                          |                     |  |                           |               |        |      |  |
| Total Gate Charge                             | $Q_g$               |  |                           | 47.2          | 70     |      |  |
| Gate-Source Charge                            | Q <sub>gs</sub>     | $V_{DS} = -15 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -12.6 \text{ A}$ |                           | 9.5           |        | nC   |  |
| Gate-Drain Charge                             | $Q_{gd}$            |  |                           | 16.6          |        | 1    |  |
| Turn-On Delay Time                            | t <sub>d(on)</sub>  |  |                           | 12            | 20     |      |  |
| Rise Time                                     | t <sub>r</sub>      | $V_{DD}$ = - 15 V, $R_L$ = 15 $\Omega$                                     |                           | 15            | 25     |      |  |
| Turn-Off Delay Time                           | t <sub>d(off)</sub> | $I_D \cong$ - 1 A, $V_{GEN}$ = - 10 V, $R_g$ = 6 $\Omega$                  |                           | 242           | 360    | ns   |  |
| Fall Time                                     | t <sub>f</sub>      |  |                           | 110           | 165    |      |  |
| Source-Drain Reverse Recovery Time            | t <sub>rr</sub>     | I <sub>F</sub> = - 2.5 A, dl/dt = 100 A/μs                                 |                           | 70            | 110    |      |  |

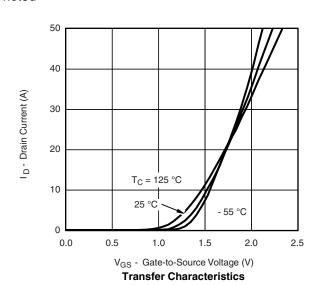
#### Notes:

- a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



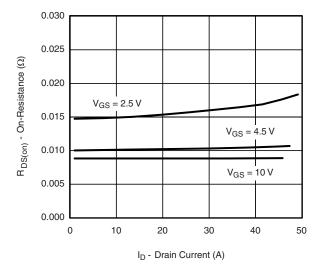




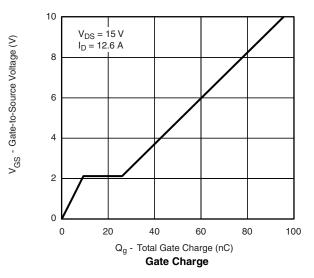


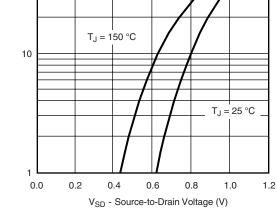


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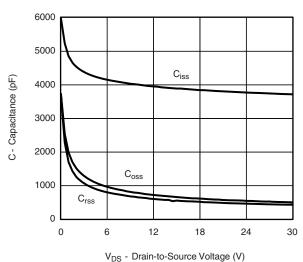


#### On-Resistance vs. Drain Current

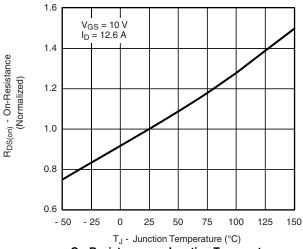




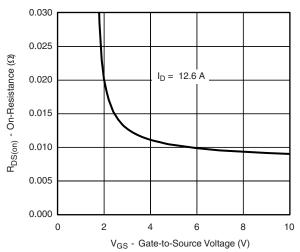
Source-Drain Diode Forward Voltage







On-Resistance vs. Junction Temperature



On-Resistance vs. Gate-to-Source Voltage

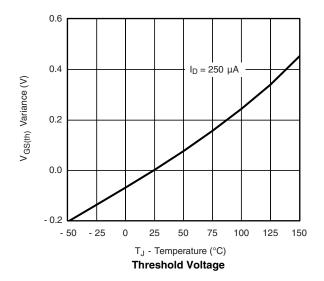
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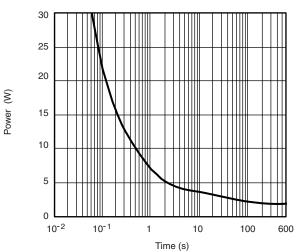
I<sub>S</sub> - Source Current (A)

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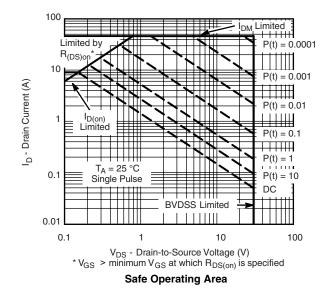
# VISHAY

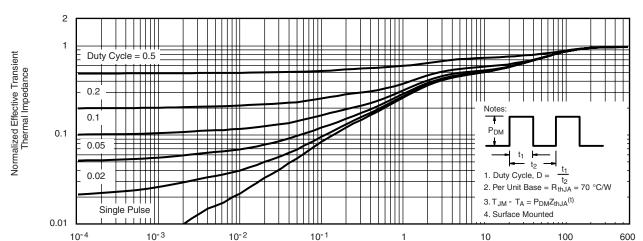
#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





Single Pulse Power, Junction-to-Ambient



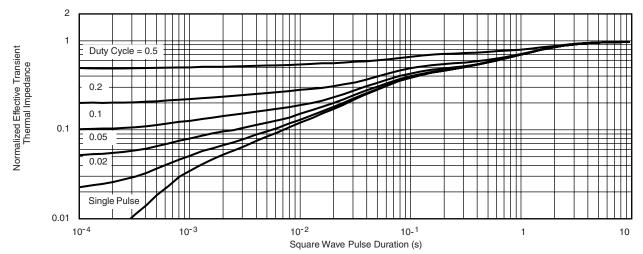


Square Wave Pulse Duration (s)

Normalized Thermal Transient Impedance, Junction-to-Ambient



#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Foot

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